## / Descriptions

TO-220FL ṂṂ Ḅ N ॐ MOS ʃ ѽ Ẓ ㄱ N-CHANNEL MOSFET in a TO-220FL Plastic Package.

## / Features

Ḥ ɔ я ɾ ᵇ ɐ ɟ ɔ ķ ɳ Ầ ʜ ѡ ỷ ỗ

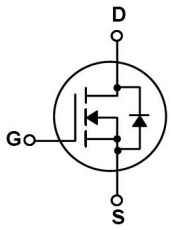
Low gate charge Low Crss Fast switching.

## / Applications

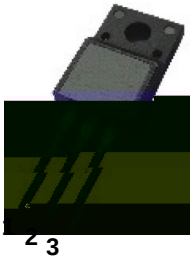
ᵹ ɤ ѽ GF2GF ᶎ Ω ᵓ ı ' Ầ ʜ

These devices are well suited for high efficiency switch mode power supplies .

## / Equivalent Circuit




## / Pinning



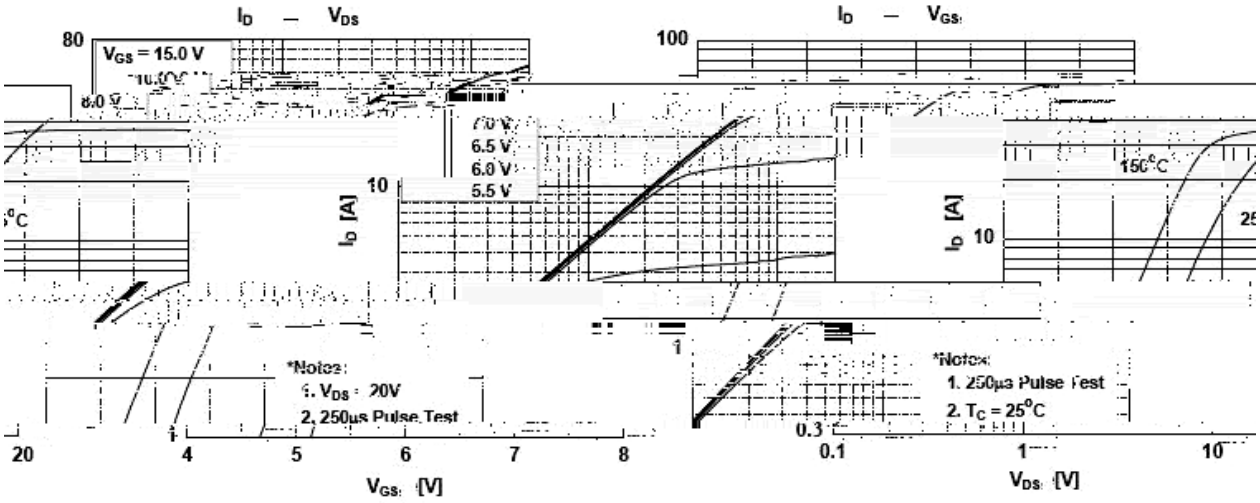

PIN1 χ G PIN 2 χ D PIN 3 χ S

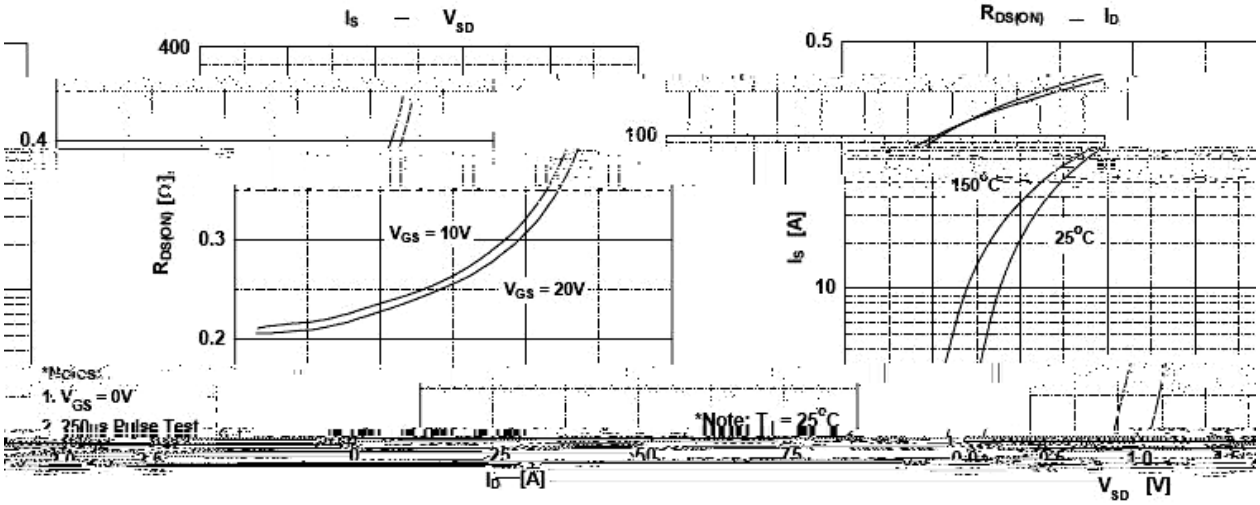
## / $h_{FE}$ Classifications & Marking

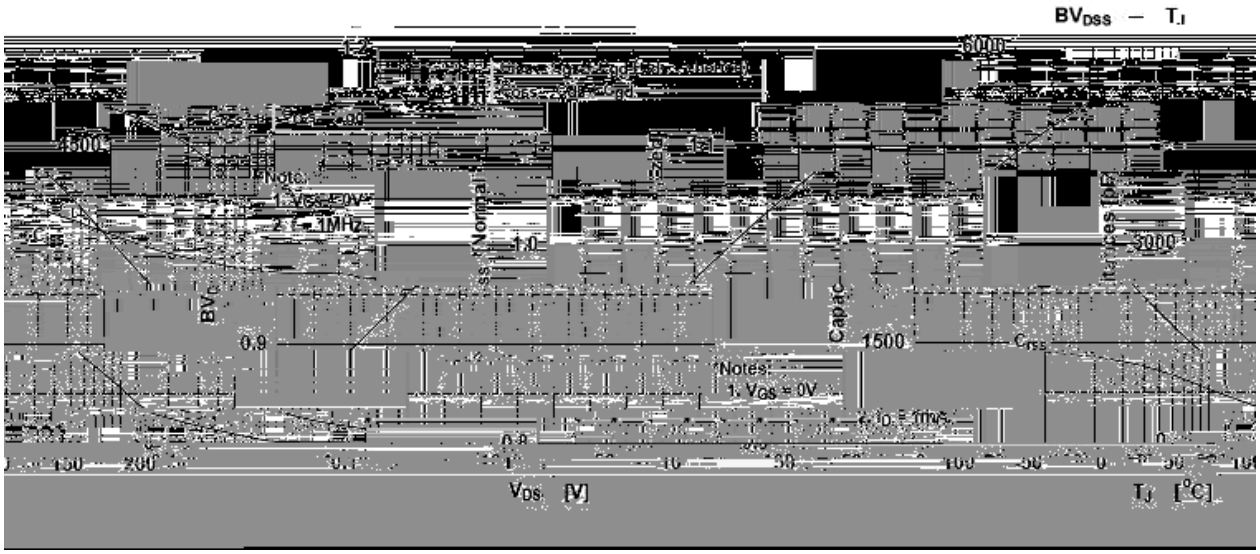
ỏ м ㄱ ب ˝ See Marking Instructions.

**BRFL20N50**

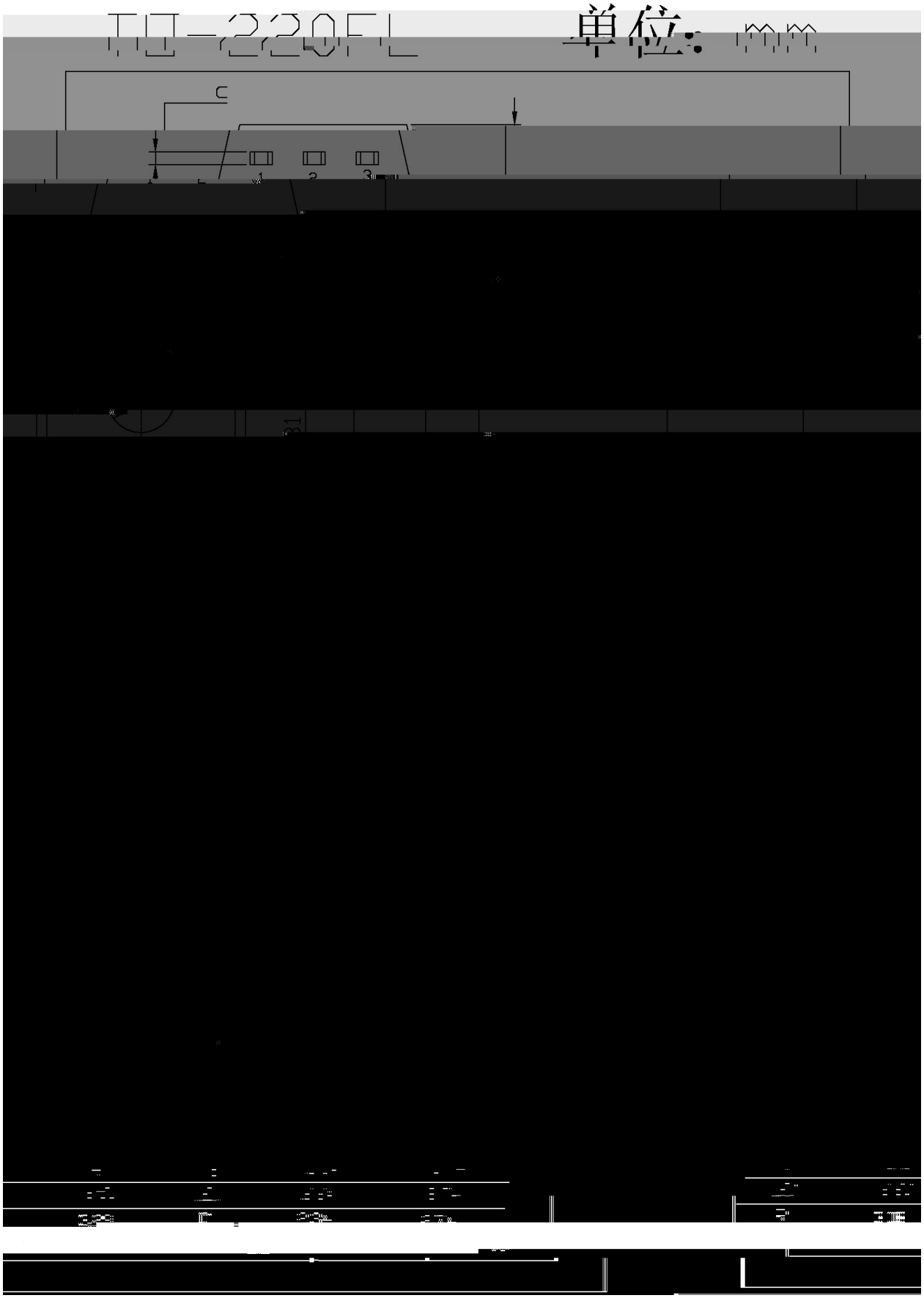
## / Electrical Characteristic Curve



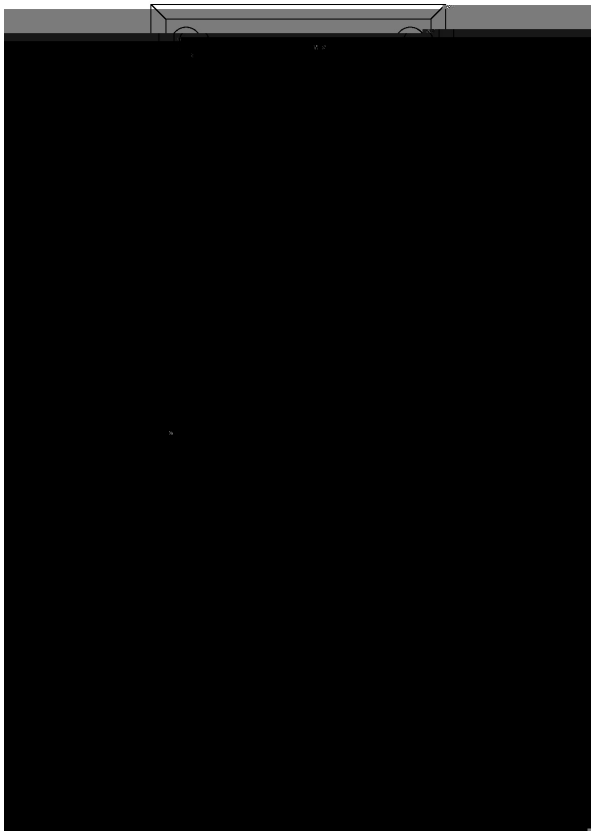



## / Package Dimensions



## / Marking Instructions



| | |
|---|---|
| BR | |
| 20N50 | |
| **** | |

Note:

| | |
|---|---|
| BR: | Company Code |
| 20N50: | Product Type. |
| ****: | Lot No. Code, code change with Lot No. |

## ( ) / Temperature Profile for Dip Soldering(Pb-Free)



ب ˝ χ

1 Ĺ ♬ □ ў 25 Ќ 150 ł ı `H ڑ 60 Ќ 90sec;

2 Š Ө □ ў 255 ° 5 ł ı `H ڑ 'Y ﾊ ㎛ 5 ° 0.5sec;

3 ì ˙ ｲ ˛ ɔ ﾑ ў ㎛ 2 Ќ 10 ł /sec.

Note:

1.Preheating:25~150 ł , Time:60~90sec.

2.Peak Temp.:255 ° 5 ł , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ł /sec.

## / Resistance to Soldering Heat Test Conditions

□ ў χ 270 ° 5 ł `H ڑ χ 10 ° 1 sec. Temp.:270±5 Time:10±1 sec

## / Packaging SPEC.

˛ ｱ ﾔ Ł / TUBE

| Package Type 封装形式 | Units 包装数量 | | | | | Dimension 包装尺寸 (unit: $mm^3$) | | |
|---|---|---|---|---|---|---|---|---|
| | 只 套管 | 套管 盒 | 只 盒 | 盒 箱 | 只 箱 | 套管 | 盒 | 箱 |
| | | | | | | | | |

## / Notices